Crystal LTD TM SPEC Form

Customer

PO# PO date

Thermoelectric module (TM) specification

<table>
<thead>
<tr>
<th>PO position #</th>
<th>TM</th>
<th>Internal Solder Melting Temp, °C</th>
<th>Max operating temperature, °C</th>
<th>Hot side temperature 25 °C</th>
<th>Rac at 25 °C</th>
<th>Ceramic size, mm</th>
<th>TM Height</th>
<th>Wire</th>
<th>Sealing</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>S-007-10-15</td>
<td>138</td>
<td>130</td>
<td>115</td>
<td>3.0</td>
<td>0.9</td>
<td>1.7</td>
<td>74.5</td>
<td>0.23</td>
</tr>
</tbody>
</table>

Clamping force: 0.8 - 1.7 kg
Max $dT$ is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.

### Q($dT$) at $Thot=298K$

- $0.1*Imax$ (0.3 A)
- $0.25*Imax$ (0.7 A)
- $0.5*Imax$ (1.5 A)
- $0.75*Imax$ (2.2 A)
- $1*Imax$ (3 A)
$U(dT)$ at $T_{hot}=298K$